[TC3] Next Generation Plasma Etching Ⅱ	
Date / Time	July 26 (Thu.), 2018 / 15:30-17:00
Place	Room C (#114)
Session Chair(s)	Nam Hun Kim (Adaptive Plasma Tech. Corp., Korea) Jason Kenney (Applied Materials, Inc., USA)

TC3-1 [Invited] **15:30-16:00**

Etching of Semiconductor Devices

Thorsten Lill, Vahid Vahedi, and Richard A. Gottscho
Lam Research Corp., USA

TC3-2 [Invited] **16:00-16:30**

Methods to Enable Plasma Etching of Transition Metals with Atomic Scale Precision

Eric A Joseph, Hiroyuki Miyazoe, Nathan Marchack, John M. Papalia, Robert Bruce, and Sebastian U. Engelmann
IBM Thomas J. Watson Research Center, USA

TC3-3 [Invited] **16:30-17:00**

Absolute Electron Density Measurements for Manufacturing-Worthy Equipment and Processes

Albert Ellingboe
Dublin City Univ., Ireland